

TENTATIVE

TOSHIBA GATE TURN-OFF THYRISTOR

SG3000GXH25

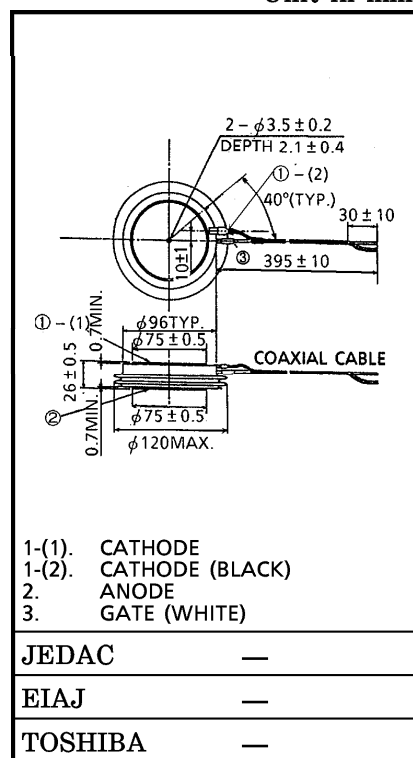
INVERTER APPLICATION

Unit in mm

- Repetitive Peak Off-State Voltage : $V_{DRM} = 4500\text{ V}$
(Note 1)
- Repetitive Peak Reverse Voltage : $V_{RRM} = 4000\text{ V}$
- R.M.S On-State Current : $I_T(\text{RMS}) = 800\text{ A}$
- Peak Turn-Off Current : $I_{TGQM} = 3000\text{ A}$
- Critical Rate of Rise of On-State Current : $di/dt = 300\text{ A}/\mu\text{s}$
- Critical Rate of Rise of Off-State Voltage : $dv/dt = 900\text{ V}/\mu\text{s}$

MAXIMUM RATINGS

| CHARACTERISTIC | SYMBOL | RATING | UNIT |
|--|-------------------|----------------|-------------------|
| Repetitive Peak Off-State Voltage (Note 1) | V_{DRM} | 4500 | V |
| Repetitive Peak Reverse Voltage | V_{RRM} | 4000 | V |
| Peak Turn-Off Current (Note 2) | I_{TGQM} | 3000 | A |
| R.M.S On-State Current (Note 3) | $I_T(\text{RMS})$ | 800 | A |
| Peak One Cycle Surge On-State Current (Non Repetitive, 10 ms-Width Half Sine Waveform) | I_{TSM} | 16000 | A |
| Critical Rate of Rise of On-State Current (Note 4) | di/dt | 300 | A / μs |
| Peak Forward Gate Current | I_{FGM} | 100 | A |
| Average Gate Power Dissipation | $P_G(\text{AV})$ | 150 | W |
| R.M.S Gate Current (Note 5) | $I_G(\text{RMS})$ | 42 | A |
| Peak Reverse Gate Voltage (At Static) | V_{RGM} | 16 | V |
| Operation Junction Temperature Range | T_j | -40~115 | °C |
| Storage Temperature Range | T_{stg} | -40~115 | °C |
| Mounting Force | — | 33.3 ± 4.9 | kN |



Weight : 1500 g

(Note 1) : $V_{GK} = -2\text{ V}$

(Note 2) : $V_D = 2400\text{ V}$, $V_{DM} \leq 3000\text{ V}$, $C_S \geq 6\ \mu\text{F}$, $di_{GQ}/dt \geq 40\text{ A}/\mu\text{s}$, $V_{DSP} \leq 800\text{ V}$,
 $L_S \leq 0.2\ \mu\text{H}$ (TOSHIBA METHOD)

(Note 3) : 50 Hz Half Sine Waveform

(Note 4) : $V_D \leq 2400\text{ V}$, $I_{TM} \leq 3000\text{ A}$, $I_G \geq 30\text{ A}$ ($t_r \leq 1\ \mu\text{s}$), $f \leq 50\text{ Hz}$, $C_S \leq 6\ \mu\text{F}$,
 $R_S \geq 10\ \Omega$, $25^\circ\text{C} \leq T_j \leq 115^\circ\text{C}$

(Note 5) : Ambient Temperature of coaxial gate-cathode lead = 90°C

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ELECTRICAL CHARACTERISTICS

| CHARACTERISTIC | SYMBOL | TEST CONDITION | MIN | TYP. | MAX | UNIT | |
|--|---------------|---|---------------------------|------|-------|---------------------------|---|
| Repetitive Peak Off-State Current | I_{DRM} | $V_{DRM} = 4500\text{ V}$, $V_{GK} = -2\text{ V}$ $T_j = 115^\circ\text{C}$ | — | — | 150 | mA | |
| Repetitive Peak Reverse Current | I_{RRM} | $V_{RRM} = 4000\text{ V}$ $T_j = 115^\circ\text{C}$ | — | — | 150 | mA | |
| Repetitive Peak Reverse Gate Current | I_{RGM} | $V_{RGM} = 16\text{ V}$ $T_j = 115^\circ\text{C}$ | — | — | 10 | mA | |
| Peak On-State Voltage | V_{TM} | $I_{TM} = 2500\text{ A}$, $T_j = 115^\circ\text{C}$ | — | — | 4.6 | V | |
| Gate Trigger Voltage | V_{GT} | $V_D = 24\text{ V}$ $R_L = 0.1\ \Omega$ | $T_j = -40^\circ\text{C}$ | — | — | 2.5 | V |
| | | | $T_j = 25^\circ\text{C}$ | — | — | 1.5 | V |
| $T_j = 0^\circ\text{C}$ | — | | — | 8.5 | A | | |
| $T_j = 25^\circ\text{C}$ | — | | — | 2.5 | A | | |
| Turn-On Delay Time | t_d | $V_D = 2250\text{ V}$, $I_{TM} = 2500\text{ A}$ $di_F/dt = 300\text{ A}/\mu\text{s}$ | — | — | 3.0 | μs | |
| Turn-On Time | t_{gt} | $I_{GM} = 30\text{ A}$ ($t_r = 1\ \mu\text{s}$) $T_j = 25^\circ\text{C}$, non-snubber | — | — | 15 | μs | |
| Critical Rate of Rise of Off-State Voltage | dv/dt | $V_{DRM} = 3000\text{ V}$ $T_j = 115^\circ\text{C}$, $V_{GK} = -4\text{ V}$ Exponential Rise | 900 | — | — | $\text{V}/\mu\text{s}$ | |
| Storage Time | t_s | $I_{TGQ} = 2500\text{ A}$ | — | — | 20 | μs | |
| Gate Turn-Off Time | t_{gq} | $V_{DM} = 3000\text{ V}$, $T_j = 115^\circ\text{C}$ | — | — | 22 | μs | |
| Tail Time | t_{tail} | $V_D = 2250\text{ V}$, $C_S = 6\ \mu\text{F}$ $di_{GQ}/dt = 50\text{ A}/\mu\text{s}$ | — | — | 250 | μs | |
| Gate Turn-Off Current | I_{GQ} | Off squeeze current $\geq 300\text{ mA}$ | — | — | 750 | A | |
| Reverse Recovery Charge | Q_{rr} | $I_T = 3000\text{ A}$, $V_R = 1500\text{ V}$ $C_S = 6\ \mu\text{F}$, $R_S = 5\ \Omega$ | — | — | 4800 | μC | |
| Reverse Recovery Current | t_{rr} | $di_T/dt = -300\text{ A}/\mu\text{s}$ $T_j = 115^\circ\text{C}$ | — | — | 10 | μs | |
| Thermal Resistance | $R_{th(j-f)}$ | Junction to fin | — | — | 0.014 | $^\circ\text{C}/\text{W}$ | |

